



## Material Content Data Sheet



<b>Sales Product Name</b>				TDA21241		<b>Issued</b>		22. January 2018	
<b>MA#</b>				MA001585402					
<b>Package</b>				PG-IQFN-30-2		<b>Weight*</b>		56.07 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.304	2.33	2.33	23265	23265	
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		82		
	non noble metal	zinc	7440-66-6	0.018	0.03		328		
	non noble metal	iron	7439-89-6	0.368	0.66		6569		
wire	non noble metal	copper	7440-50-8	14.956	26.67	27.37	266746	273725	
	non noble metal	copper	7440-50-8	0.085	0.15	0.15	1509	1509	
	encapsulation	organic material	carbon black	1333-86-4	0.047	0.08		829	
glue	plastics	epoxy resin	-	2.395	4.27		42710		
	inorganic material	silicondioxide	60676-86-0	20.809	37.12	41.47	371125	414664	
leadfinish	non noble metal	tin	7440-31-5	0.593	1.06	1.06	10572	10572	
plating	noble metal	silver	7440-22-4	0.040	0.07	0.07	716	716	
glue	plastics	epoxy resin	-	0.088	0.16		1576		
	noble metal	silver	7440-22-4	0.265	0.47	0.63	4729	6305	
solder	noble metal	silver	7440-22-4	0.029	0.05		522		
	non noble metal	tin	7440-31-5	0.023	0.04		418		
	non noble metal	lead	7439-92-1	1.118	1.99	2.08	19938	20878	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		14		
	non noble metal	zinc	7440-66-6	0.003	0.01		55		
	non noble metal	iron	7439-89-6	0.062	0.11		1099		
	non noble metal	copper	7440-50-8	2.502	4.46	4.58	44622	45790	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.01		61		
	non noble metal	zinc	7440-66-6	0.014	0.02		243		
	non noble metal	iron	7439-89-6	0.273	0.49		4862		
	non noble metal	copper	7440-50-8	11.069	19.74	20.26	197410	202576	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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